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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74LVC16540

16-bit Buffers / Line Drivers with 3-state Outputs



ADE-205-057B(Z)

Rev.2
September 1995

Description

The HD74LVC16540 has sixteen inverter drivers with three state outputs in a 48 pin package. When $\overline{G}1$ and $\overline{G}2$ is low level, this drivers set up output is enable. Low voltage and high speed operation is suitable at the battery drive product (note type personal computer) and low power consumption extends the life of a battery for long time operation.

Features

- $V_{CC} = 2.0\text{ V to }5.5\text{ V}$
- All inputs $V_{IH}(\text{Max.}) = 5.5\text{ V} (@V_{CC} = 0\text{ V to }5.5\text{ V})$
- Typical V_{OL} ground bounce $< 0.8\text{ V} (@V_{CC} = 3.3\text{ V}, T_a = 25^\circ\text{C})$
- Typical V_{OH} undershoot $> 2.0\text{ V} (@V_{CC} = 3.3\text{ V}, T_a = 25^\circ\text{C})$
- High output current $\pm 24\text{ mA} (@V_{CC} = 3.0\text{ V to }5.5\text{ V})$

Function Table

Inputs			Output Y
$\overline{G}1$	$\overline{G}2$	A	
L	L	L	H
L	L	H	L
H	X	X	Z
X	H	X	Z

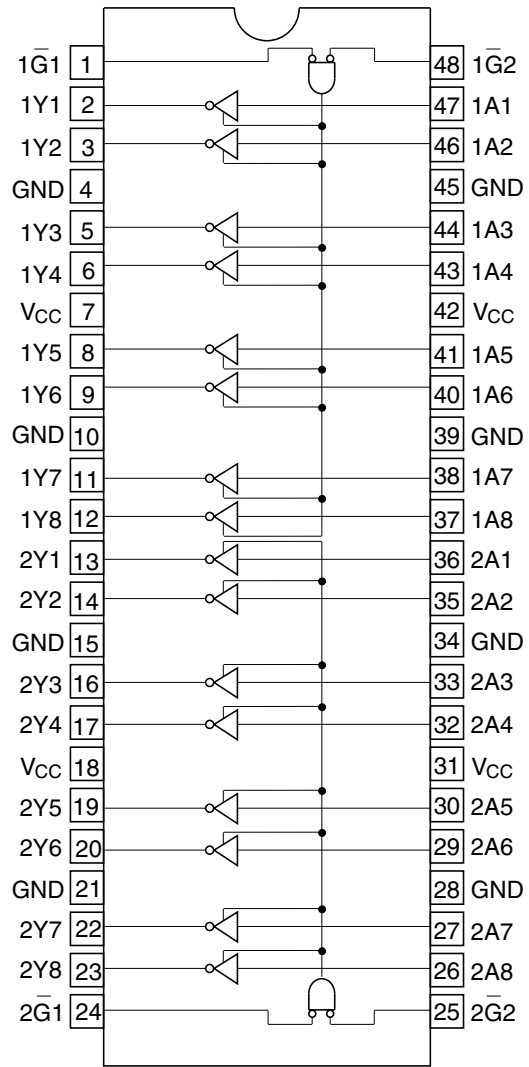
H : High level

L : Low level

X : Immaterial

Z : High impedance

Pin Arrangement



(Top view)

Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V_{CC}	-0.5 to 6.0	V	
Input diode current	I_{IK}	-50	mA	$V_I = -0.5\text{ V}$
Input voltage	V_I	-0.5 to 6.0	V	
Output diode current	I_{OK}	-50	mA	$V_O = -0.5\text{ V}$
		50	mA	$V_O = V_{CC} + 0.5\text{ V}$
Output voltage	V_O	-0.5 to $V_{CC} + 0.5$	V	
Output current	I_O	± 50	mA	
V_{CC} , GND current / pin	I_{CC} or I_{GND}	100	mA	
Storage temperature	Tstg	-65 to +150	°C	

Note: The absolute maximum ratings are values which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V_{CC}	1.5 to 5.5	V	Data retention
		2.0 to 5.5	V	At operation
Input / output voltage	V_I	0 to 5.5	V	\overline{G} , A
	V_O	0 to V_{CC}	V	Y
Operating temperature	Ta	-40 to 85	°C	
Output current	I_{OH}	-12	mA	$V_{CC} = 2.7\text{ V}$
		-24 ^{*2}	mA	$V_{CC} = 3.0\text{ V to } 5.5\text{ V}$
	I_{OL}	12	mA	$V_{CC} = 2.7\text{ V}$
		24 ^{*2}	mA	$V_{CC} = 3.0\text{ V to } 5.5\text{ V}$
Input rise / fall time ^{*1}	t_r, t_f	10	ns/V	

Notes: 1. This item guarantees maximum limit when one input switches.

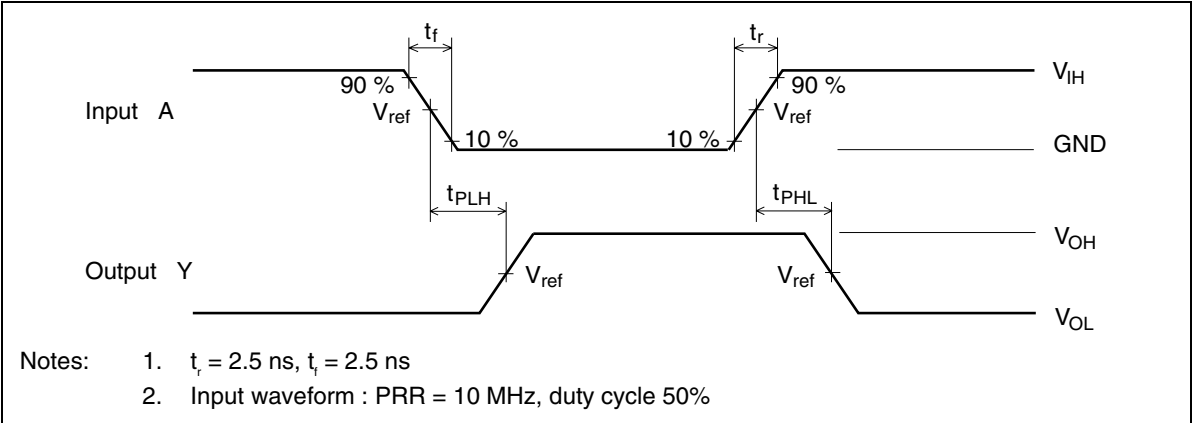
Waveform : Refer to test circuit of switching characteristics.

2. duty cycle $\leq 50\%$

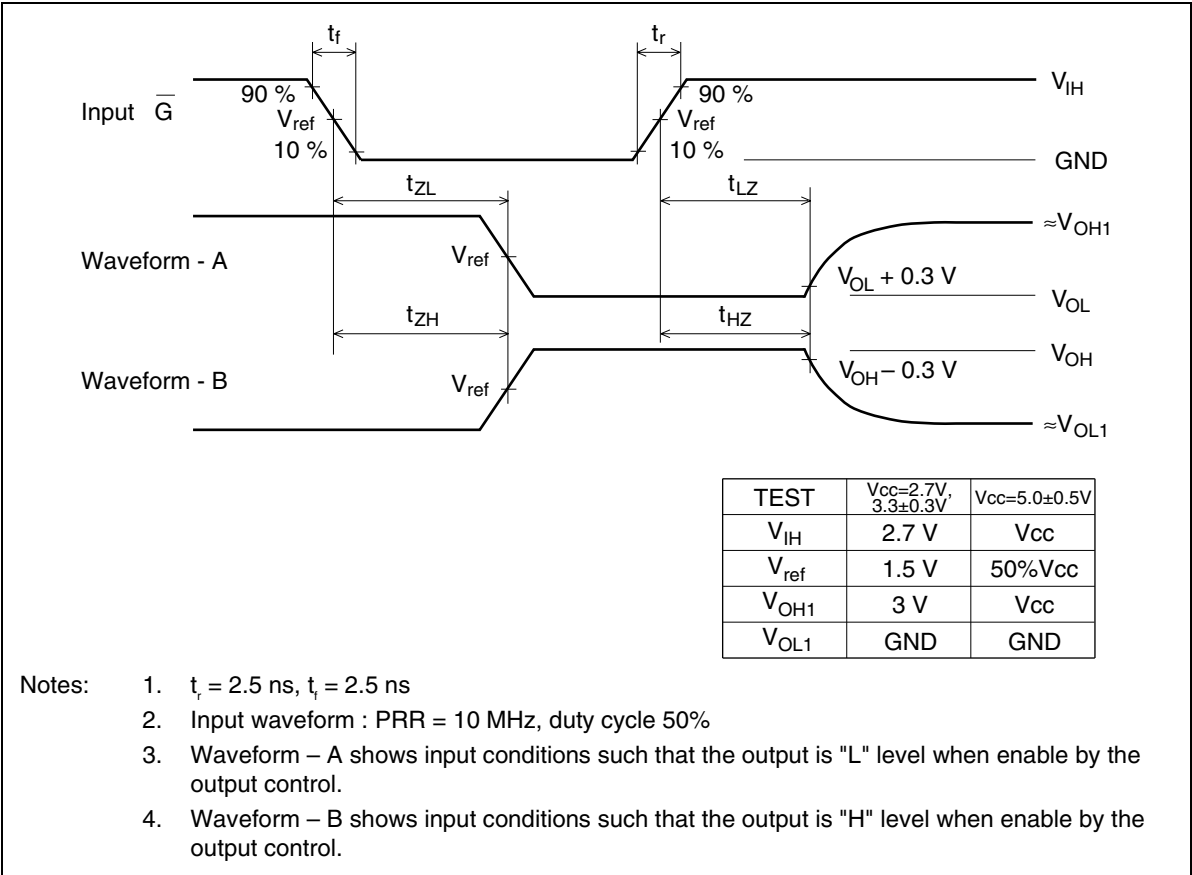
Electrical Characteristics

Item	Symbol	V_{CC} (V)	Ta = -40 to 85°C		Unit	Test Conditions
			Min	Max		
Input voltage	V_{IH}	2.7 to 3.6	2.0	—	V	
		4.5 to 5.5	$V_{CC} \times 0.7$	—	V	
	V_{IL}	2.7 to 3.6	—	0.8	V	
		4.5 to 5.5	—	$V_{CC} \times 0.3$	V	
Output voltage	V_{OH}	2.7 to 5.5	$V_{CC} - 0.2$	—	V	$I_{OH} = -100 \mu A$
		2.7	2.2	—	V	$I_{OH} = -12 \text{ mA}$
		3.0	2.4	—	V	
		3.0	2.0	—	V	$I_{OH} = -24 \text{ mA}$
		4.5	3.8	—	V	
	V_{OL}	2.7 to 5.5	—	0.2	V	$I_{OL} = 100 \mu A$
		2.7	—	0.4	V	$I_{OL} = 12 \text{ mA}$
		3.0	—	0.55	V	$I_{OL} = 24 \text{ mA}$
		4.5	—	0.55	V	
Input current	I_{IN}	0 to 5.5	—	± 5.0	μA	$V_{IN} = 5.5 \text{ V or GND}$
Off state output current	I_{OZ}	5.5	—	± 10	μA	$V_{IN} = V_{CC}, \text{ GND}$ $V_{OUT} = V_{CC} \text{ or GND}$
Quiescent supply current	I_{CC}	5.5	—	40	μA	$V_{IN} = V_{CC} \text{ or GND}$
	ΔI_{CC}	3.0 to 3.6	—	500	μA	$V_{IN} = \text{one input at } (V_{CC} - 0.6) \text{ V,}$ other inputs at $V_{CC} \text{ or GND}$

Waveforms – 1

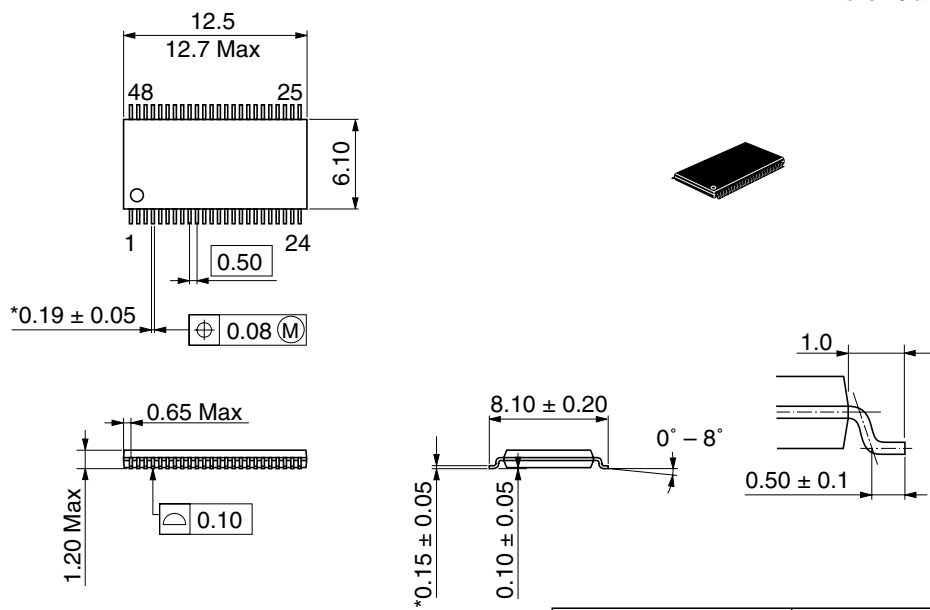


Waveforms – 2



Package Dimensions

As of July, 2001
Unit: mm



*Pd plating

Hitachi Code	TTP-48DBV
JEDEC	—
JEITA	—
Mass (reference value)	0.20 g

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